



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 431 I/O FC BGA, 20 X 20 PKG, 0.8 MM PITCH, WITH LID AND CAP ZONES	DOCUMENT NO: 98ARE10549D	REV: C	
	CASE NUMBER: 1550-03	19 SEP 2005	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. FEATURES ARE SYMMETRICAL ABOUT THE PACKAGE CENTER LINES UNLESS DIMENSIONED OTHERWISE.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
8. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.
9. FC CBGA (CERAMIC) PACKAGE CODE: 5238
FC PBGA (PLASTIC) PACKAGE CODE: 5263
10. PIN 1 INDICATOR CAN BE IN THE FORM OF NUMBER 1 MARKING OR AN "L" SHAPE MARKING

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 431 I/O FC BGA, 20 X 20 PKG, 0.8 MM PITCH, WITH LID AND CAP ZONES	DOCUMENT NO: 98ARE10549D	REV: C	
	CASE NUMBER: 1550-03	19 SEP 2005	
	STANDARD: NON-JEDEC		